

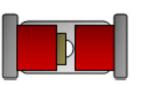
150mW Bi-directional Trigger Diode

FEATURES

- Surface mounted device
- Hermetically sealed glass
- Matte Tin(Sn) terminal finish
- All external surfaces are corrosion resistant and terminals are readily solderable

MECHANICAL DATA

- Case: Mini-MELF package
- High temperature soldering guaranteed: 260°C/10s
- Weight: 29 ± 2.5 mg
- Terminal: Pure tin plated, lead free,
- solderable per MIL-STD-202, method 208 guaranteed
- Pb free and RoHS compliant





Hermetically Sealed Glass



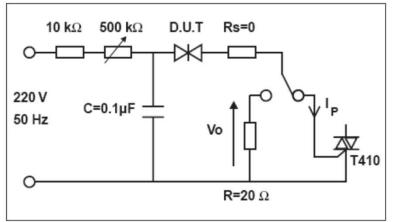
MAXIMUM RATINGS AND ELECTRICAL CHARA	CTERISTIC	CS (T _A =25°C unless otherwise noted)
PARAMETER	SYMBOL	VALUE

PARAMETER		SYMBOL	VALUE	UNIT
Repetitive Peak Forward Current	Pulse Width = 20µs	I _{FRM}	2	A
Power Dissipation		PD	150	mW
Thermal Resistance (Junction to Ambient) (Note)	R _{θJA}	400	°C/W
Junction and Storage Temperature Range	9	T _J , T _{STG}	- 40 to + 125	۵°

Notes: Valid provided that electrodes are kept at ambient temperature

PARAMETER			MIN TYP		MAX	TEST CONDITION	UNIT	
Break-Over Voltage	LLDB3	V _{BO}	28	32	36	C=22nF	V	
Break-Over voltage	LLDB3TG	V BO	30	32	34	C=22IIF		
Break-Over Voltage Symmetry	LLDB3	+ / -V _{BO}			±3	C=22nF	V	
Break-Over voltage Symmetry	LLDB3TG	+/-v _{BO}			±2	C=ZZIIF	V	
Dynamic Breakdown Voltage	LLDB3	۵V	5			I _{BO} to I _F =10mA	V	
Dynamic Breakdown voltage	LLDB3TG	<i>△</i> v	9				mA V	
Output Voltage		Vo	5			(Note)	V	
Leakage Current		Ι _Β			10	$V_B = 0.5 V_{BO} (Max)$	μA	
Break-Over Current	LLDB3				100	C=22nF		
Dieak-Over Current	LLDB3TG	I _{BO}	-		15	0=2211F	μA	

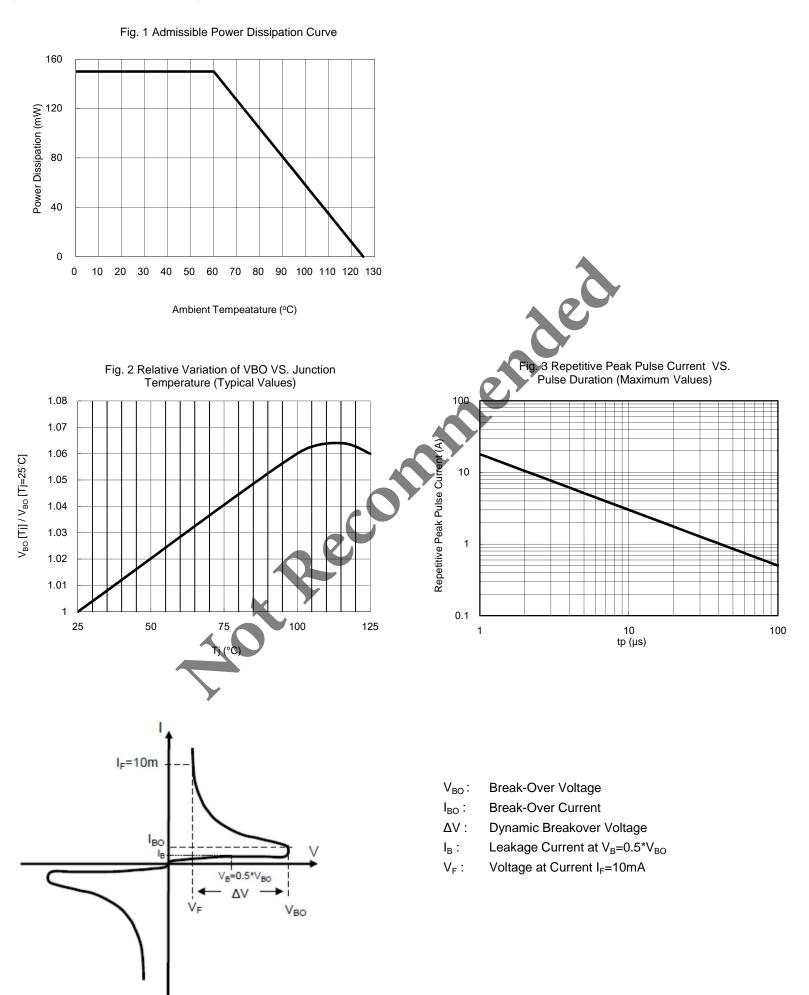
Notes: Test Circuit





RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)





Taiwan Semiconductor

Small Signal Product

ORDERING INFORMATION						
PART NO.	MANUFACTURE CODE (Note)	PACKING CODE	GREEN COMPOUND CODE	PACKAGE	PACKING	MARKING
LLDB3		L1	G	Mini-MELF (LL34)	2.5K / 7" Reel	
LLDB3TG		L1	G	Mini-MELF (LL34)	2.5K / 7" Reel	

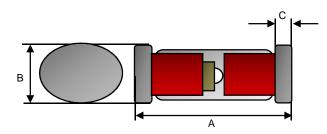
Note: Indicator of manufacturing site for manufacture special control, if empty means no special control requirement

XAMPLE					
PREFERRED P/N	PART NO.	MANUFACTURE CODE	PACKING CODE	GREEN COMPOUND CODE	DESCRIPTION
LLDB3 L1G	LLDB3		L1	G	Green compound
LLDB3-N0 L1G	LLDB3	N0	L1	G	Green compound
		NO	omb		



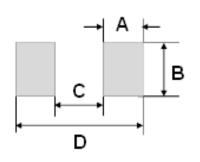
PACKAGE OUTLINE DIMENSIONS

Mini-MELF (LL34)



DIM.	Unit	(mm)	Unit (inch)	
	Min	Max	Min	Max
А	3.30	3.70	0.130	0.146
В	1.40	1.60	0.055	0.063
С	0.20	0.50	0.008	0.020

SUGGESTED PAD LAYOUT



		DIM.	Unit (mm)	Unit (inch)
			Тур.	Тур.
		А	1.25	0.049
	A.	В	2.00	0.079
		С	2.50	0.098
		D	5.00	0.197
200				





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